



COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Product Summary

Device	V _{(BR)DSS}	R _{DS(ON)}	I _D T _A = +25°C
Q1	25V	4Ω @ $V_{GS} = 4.5V$	0.5A
Q2	-12V	55mΩ @ V _{GS} = -4.5V	-3.9A
Q2	-120	-3.5A	

Description

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

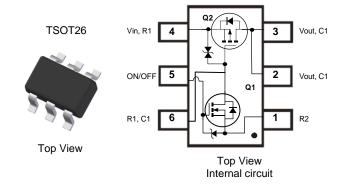
- DC-DC Converters
- Power Management Functions
- Load Switch

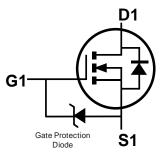
Features and Benefits

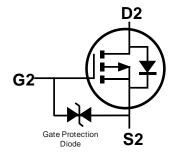
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: TSOT26
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.013 grams (Approximate)







Q1 N-Channel MOSFET

Q2 P-Channel MOSFET

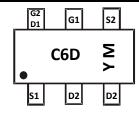
Ordering Information (Note 4)

Part Number	Case	Packaging
DMC25D1UVT-7	TSOT26	3000 / Tape & Reel
DMC25D1UVT-13	TSOT26	10000 / Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



C6D = Product Type Marking Code YM or YM = Date Code Marking Y or \overline{Y} = Year (ex: C = 2015) M = Month (ex: 9 = September)

Date Code Key

Year	201	5	2016		2017	20	18	2019		2020	2	2021	
Code	С		D		E	F		G		Н		I	
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec	
Code	1	2	3	4	5	6	7	8	9	0	N	D	



Maximum Ratings – Q1 (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	25	V
Gate-Source Voltage	V _{GSS}	-0.5 +8	V
Continuous Drain Current (Note 5) V _{GS} = 4.5V	I _D	0.5	Α
Maximum Continuous Body Diode Forward Current (Note 6)	I _S	1.2	Α
Pulsed Drain Current (Note 6)	I _{DM}	1.5	Α

Maximum Ratings – Q2 (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V_{DSS}	-12	V
Gate-Source Voltage		V_{GSS}	8±	V
Continuous Drain Current (Note 5) \/ 45\/	Steady State		-3.9	Α
Continuous Drain Current (Note 5) V _{GS} = -4.5V Note 9		I_{D}	-17.4	Α
Continuous Drain Current (Note 5) V _{GS} = -2.5V		-2.82	Α	
Maximum Continuous Body Diode Forward Current (Note 6)	Is	-40	Α	
Pulsed Drain Current (Note 6)		I _{DM}	-40	Α

Thermal Characteristics

Characteristic		Symbol	Value	Unit	
Power Dissipation (Note 5)		P_D	1.3	W	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	D	100	°C/W	
Thermal Resistance, Junction to Ambient (Note 5)	Note 9	$R_{\theta JA}$	5		
Thermal Resistance, Junction to Case (Note 5)	$R_{ heta JC}$	36	°C/W		
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C		

Electrical Characteristics - Q1 (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	25	_	_	V	$V_{GS} = 0V, I_{D} = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 20V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	100	nA	$V_{GS} = 8V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	0.65	0.85	1.5	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	l	3.8	4	Ω	$V_{GS} = 4.5V, I_D = 0.4A$	
Diode Forward Voltage	V_{SD}	_	0.76	1.2	V	$V_{GS} = 0V, I_{S} = 0.29A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss		27.6	_		V _{DS} = 10V, V _{GS} = 0V, f = 1.0MHz	
Output Capacitance	Coss	l	8.5	_	pF		
Reverse Transfer Capacitance	Crss		3.3	_		1 = 1.0lvii iz	
Gate Resistance	R_g	_	25	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Q_g	_	0.4	_			
Total Gate Charge (V _{GS} = 10V)	Q_g	_	0.9	_	nC	V 5V 1 00A	
Gate-Source Charge	Q_{gs}	_	0.1	_	IIC	$V_{DS} = 5V, I_{D} = 0.2A$	
Gate-Drain Charge	Q_{gd}	_	0.04	_			
Turn-On Delay Time	t _{D(ON)}	_	2.5	_			
Turn-On Rise Time	t _R	_	1.4	_	ns	$V_{GS} = 4.5V, V_{DS} = 6V,$	
Turn-Off Delay Time	t _{D(OFF)}	_	5.7	_	115	$R_G = 50\Omega, I_D = 0.5A$	
Turn-Off Fall Time	t _F	ı	4.3	_			

Notes:

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1in. square copper plate.
 6. Repetitive rating, pulse width limited by junction temperature.
 7. Short duration pulse test used to minimize self-heating effect.
 8. Guaranteed by design. Not subject to production testing.
 9. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%.



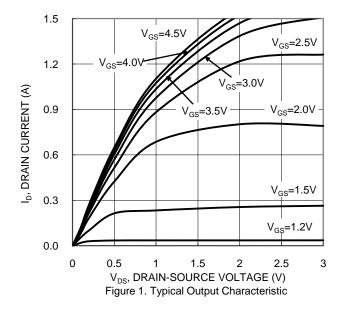
Electrical Characteristics – Q2 (@T_A = +25°C, unless otherwise specified.)

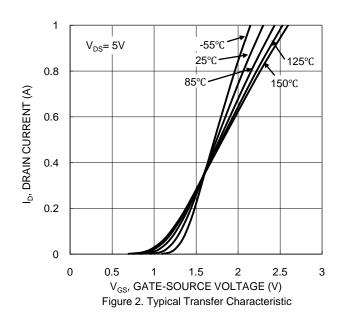
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 10)	•					•
Drain-Source Breakdown Voltage	BV _{DSS}	-12	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	1	_	-1	μΑ	$V_{DS} = -6.4V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 8V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 10)						
Gate Threshold Voltage	V _{GS(TH)}	-0.35	_	-1.5	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$
		I	_	55		$V_{GS} = -4.5V$, $I_D = -2.8A$
Static Drain-Source On-Resistance	R _{DS(ON)}	l	_	70	mΩ	$V_{GS} = -2.5V$, $I_D = -2.5A$
	, ,	_		100		$V_{GS} = -1.8V, I_{D} = -2.0A$
Diode Forward Voltage	V_{SD}	_	_	-1.2	V	$V_{GS} = 0V, I_{S} = -0.6A$
DYNAMIC CHARACTERISTICS (Note 11)						
Input Capacitance	C _{iss}	l	9.7	_		., ., ., .,
Output Capacitance	Coss	_	393	_	pF	$V_{DS} = -6V$, $V_{GS} = 0V$, $f = 1MHz$
Reverse Transfer Capacitance	C _{rss}	_	1.9	_		
Gate Resistance	Rg	_	1846	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (V _{GS} = -4.5V)	Qg	_	24.5	_		
Gate-Source Charge	Qgs	_	3.3	_	nC	$V_{DS} = -6V, I_{D} = -2.8A$
Gate-Drain Charge	Q _{gd}	_	7.3	_		
Turn-On Delay Time	t _{D(ON)}	_	1.2	_		
Turn-On Rise Time	t _R	_	2.7	_	1	$V_{GS} = -4.5V, V_{DS} = -6V,$
Turn-Off Delay Time	t _{D(OFF)}	_	9.8	_	μs	$R_G = 6\Omega$, $I_D = -2.8A$
Turn-Off Fall Time	t _F	_	6.5	_	1	

Notes:

- 10. Short duration pulse test used to minimize self-heating effect.
- 11. Guaranteed by design. Not subject to production testing.

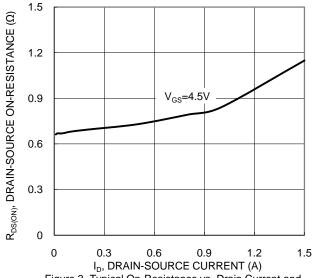
Typical Characteristics - N-CHANNEL

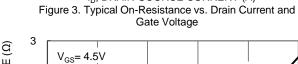












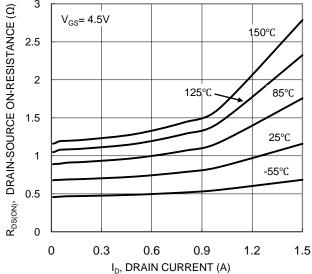


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

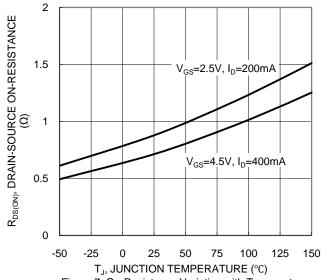
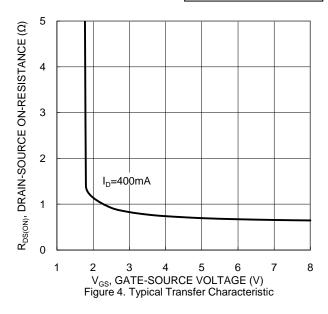


Figure 7. On-Resistance Variation with Temperature



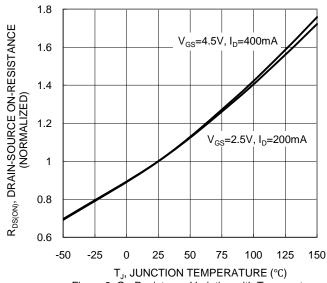
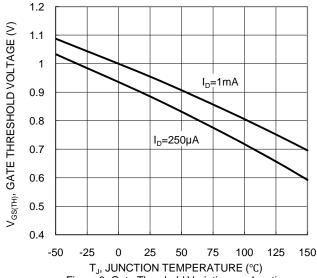
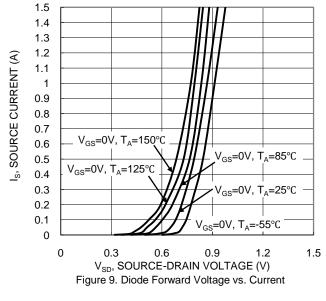


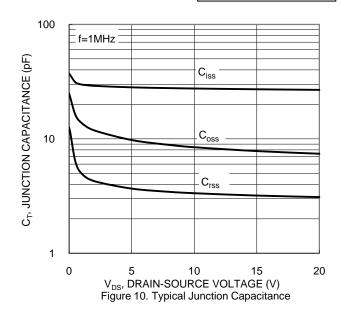
Figure 6. On-Resistance Variation with Temperature

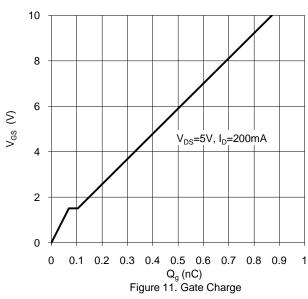


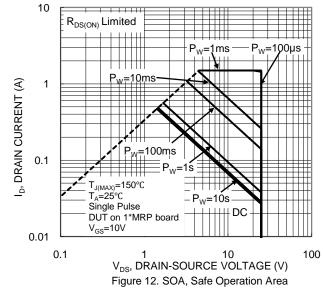
T_J, JUNCTION TEMPERATURE (°C) Figure 8. Gate Threshold Variation vs. Junction Temperature











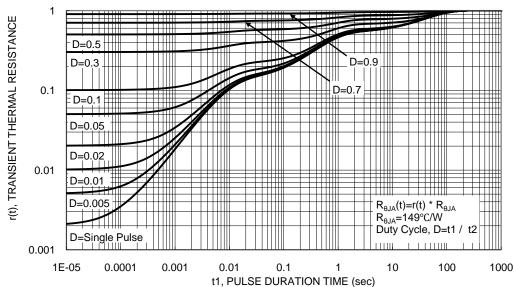
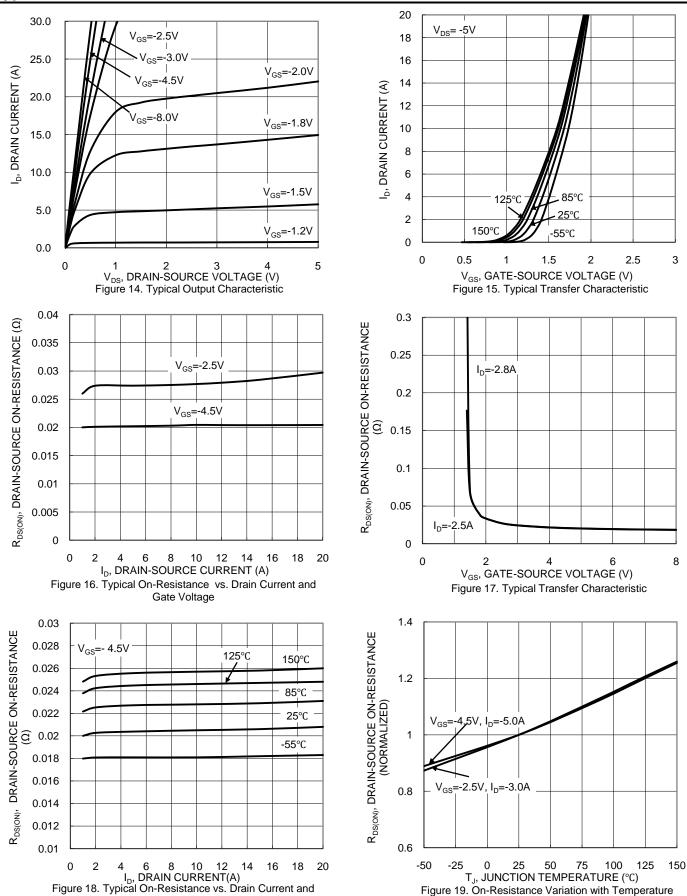


Figure 13. Transient Thermal Resistance



Typical Characteristics - P-CHANNEL

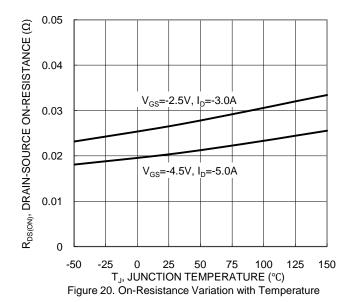


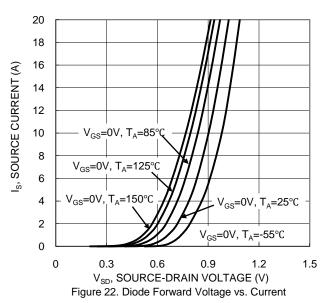
Temperature

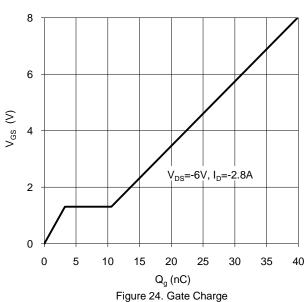
Figure 19. On-Resistance Variation with Temperature

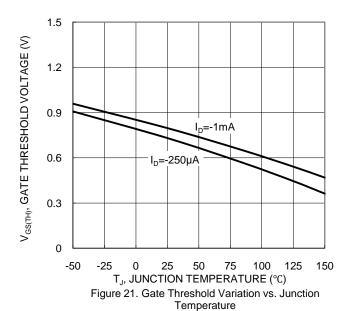


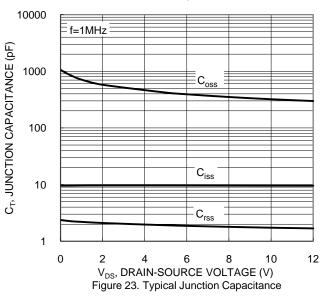


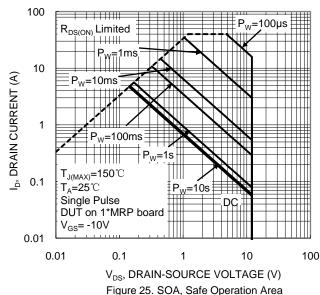






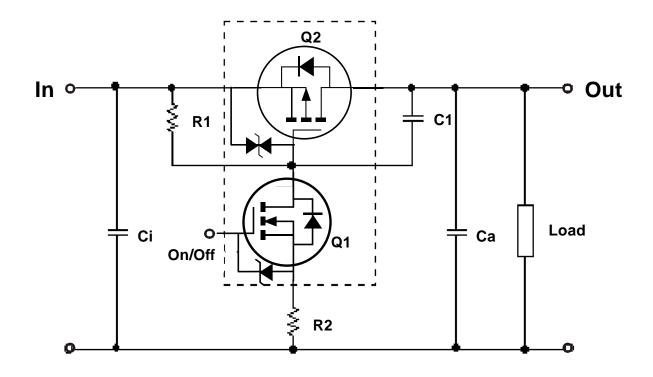






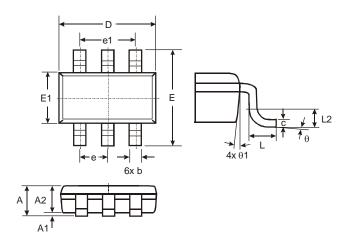


Application Circuit



Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

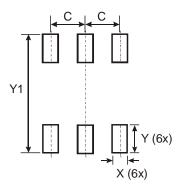


TSOT26						
Dim	Min	Max	Тур			
Α	-	1.00	1			
A 1	0.01	0.10	1			
A2	0.84	0.90	1			
D	_	_	2.90			
Е	-	_	2.80			
E1	_	_	1.60			
b	0.30	0.45	_			
C	0.12	0.20	1			
е	_	_	0.95			
e1	_	_	1.90			
٦	0.30	0.50				
L2	-	_	0.25			
θ	0°	8°	4°			
θ1	4°	12°	_			
All D	All Dimensions in mm					



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.950
Х	0.700
Υ	1.000
Y1	3.199

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